ABSTRACT

A method for marking a wafer that is cut from a boule. A surface of the boule is marked with an encoded marking that extends completely along a distance of the boule that is used for cutting wafers. The encoded marking is disposed substantially parallel to a length axis of the boule. The wafer is cut from the boule from within the distance, such that the encoded marking along the surface of the boule is disposed at a peripheral edge of the wafer. The encoded marking contains information in regard to the wafer.

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